



I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

By: Manfred Beck

Date: April 16, 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Nicolas Nagel et al.

Applic. No. : 09 729,069

Filed : December 4, 2000

Title : Microelectronic Structure and Method of
Fabricating it

P R E L I M I N A R Y A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Responsive to the Notice to File Missing Parts dated February
20, 2001 kindly amend the above-identified application as
follows:

In the Specification:

Please replace the paragraph on page 20, lines 12-14 with the
following paragraph.